

BACKGROUND

The glass transition is the temperature range where amorphous structure undergoes a change in mobility which can have a large effect on material properties. This transition is a reversible transition, unless there is some structure change in the material that would eliminate or obscure the transition. As a material is heated from below the glass transition temperature (T_g) through the T_g , the molecular mobility increases. Conversely, as a material is cooled from above the T_g through the T_g , the molecular mobility decreases.

There are several characterization techniques that can be used to measure a glass transition, including DSC, DMA, & TMA. DSC is routinely used due to speed and ease of sampling. As a material is heated (or cooled) through a T_g , there is a step transition in the DSC heat flow rate. This transition is typically analyzed to find the midpoint, and the midpoint is called the T_g . This midpoint can be determined in several ways with the half height method (half the height of the change in C_p) and the inflection point being the most common. Depending upon the thermal history of a material, the glass transition as seen in a DSC can be a simple step transition, or much more complicated and therefore harder to interpret. This application note will show how Modulated DSC® (MDSC®) can be used to improve the interpretation of these transitions.

DSC

Differential Scanning Calorimetry (DSC) is a technique that measures heat flow rate of a sample versus temperature, or versus time at a temperature. With typical samples sizes of 5-10 mg, and heating rates of 10-20 °C/min, DSC is a standard thermal technique to look at glass transitions, and other transitions of materials. As the molecular mobility increases upon heating through the T_g , the heat capacity (C_p) also increases. This step change in C_p , shows up as a step transition in heat flow.

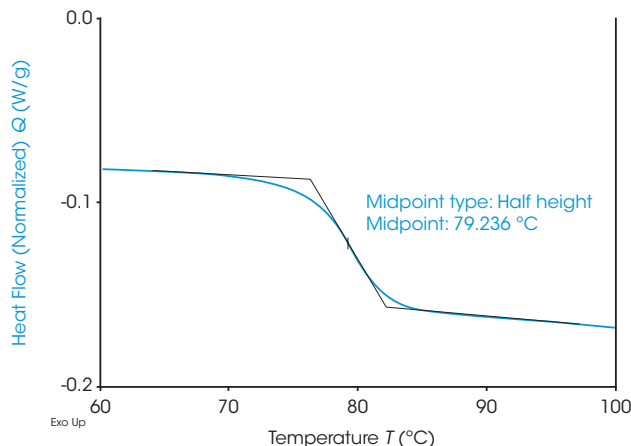


Figure 1. Simple Step change at Polymer T_g by DSC

Theoretically, the glass transition in a DSC scan is a simple step transition in the endothermic direction. This size of this step transition varies with the amount of amorphous structure, the sample size, and the heating rate. Figure 1 shows a simple step change occurring at a glass transition.

PEAK AT THE GLASS TRANSITION

Sometimes the transition is not so simple. Due to thermal history, and/or physical stresses, the step change may have a large endothermic peak instead of a simple step change. Sometimes this peak can be so large it can be misinterpreted as a melt instead of a glass transition. This peak is called an enthalpic recovery peak. Figure 2 shows an example of a material with an enthalpic recovery peak at the glass transition. The peak is commonly caused by a material being stored at a temperature below, but close to, the T_g [1]. In these cases, the material's temperature is close enough to the T_g that it has a little molecular mobility. Over time, the material can give up energy and move to a lower energy state. This is a time dependent event (Kinetic event) and occurs faster the closer to the T_g the sample is stored. Typically, if a material is stored more than 40 °C below the T_g , this occurs so slowly as to be negligible. As this lower energy material is heated through T_g , there is the normal increase in mobility that occurs at the T_g . In addition, the sample is in a lower energy state than expected and absorbs that energy as the molecular mobility increases. This energy absorbance shows up as an endothermic peak at the T_g .

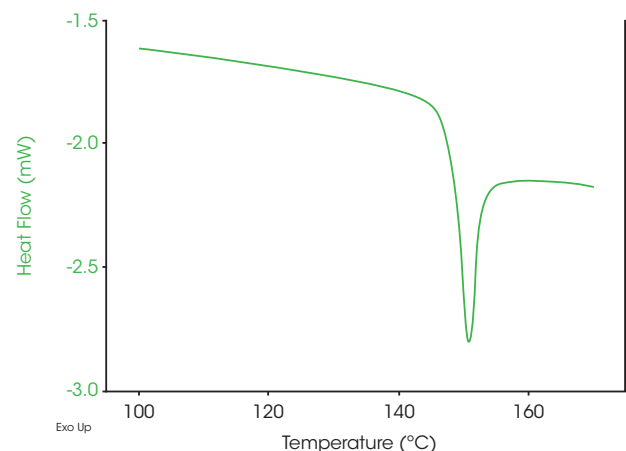


Figure 2. Example of a Polymer T_g with an Enthalpic Recovery Peak

The existence of this peak makes it difficult to determine the midpoint of the transition. In addition, these materials are at a lower energy state than normal with lower molecular mobility. This lower molecular mobility can shift the “apparent” T_g , to a higher temperature. One way to try and eliminate this enthalpic recovery peak is to heat the material 15-20 °C above the T_g , cool

down and then reheat. This can work; however, it is problematic for thermosets and materials that might change during this heating past the T_g. For instance, if the goal is to obtain the T_g of a thermoset after “x” hours of curing at room temperature, this typically won’t work as the sample will advance the cure and the measured T_g on the second heat will be higher than on the first heat. This can also be an issue with some thermoplastics as some semi-crystalline thermoplastics will increase crystallinity when heated past the T_g.

For many materials, the answer is MDSC!

MODULATED DSC® (MDSC®)

Modulated DSC is a technique where a sinusoidal temperature modulation is overlaid on the normal heating rate of a DSC experiment.[2] MDSC is a standard feature on the Discovery DSC 2500, and all current TA Instruments DSC’s including the new Discovery X3 DSC. MDSC allows the separation of Heat Capacity events from Kinetic events. As already mentioned, the glass transition is due to a change in heat capacity and the enthalpic recovery is a kinetic event. The output of a MDSC experiment includes the Total Heat Flow (the same as a standard DSC heat flow at the same underlying heating rate), Reversing Heat Flow (the heat capacity component of heat flow), and the Non-Reversing Heat Flow (the kinetic component of heat flow).[3] As a glass transition is a heat capacity event it will appear in the Reversing Heat Flow, and as the enthalpic recovery is a kinetic event it will appear in the Non-Reversing Heat Flow. Figure 3 shows the relationship between transitions and the MDSC signals.

MDSC Theory: Heat Flow Signals

$$\frac{dQ}{dt} = C_p \frac{dT}{dt} + f(T, t)$$

<p>Total Heat Flow</p> <ul style="list-style-type: none"> • All Transitions 	<p>Reversing Heat Flow</p> <ul style="list-style-type: none"> • Heat Capacity • Glass Transition • Melting 	<p>Non-Reversing Heat Flow</p> <ul style="list-style-type: none"> • Enthalpic Recovery • Evaporation • Crystallization • Thermoset Cure • Denaturation • Decomposition • Some Melting • Chemical Reactions
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Figure 3. MDSC Heat flow Signals and Transitions

MDSC Conditions:

A typical MDSC experimental procedure is listed below for the determination of a glass transition:

- Data Storage Off
- Equilibrate at 0 °C
- Modulate ±1 °C every 60 seconds
- Isothermal for 5 minutes
- Data Storage On
- Ramp 3 °C/min to 200 °C

The starting and final temperature should be adjusted as appropriate for the sample. A good starting point is at least 20 °C below any expected transitions, and a final temperature of at least 20 °C above any sample transitions. It is recommended that the final temperature be kept lower than the decomposition temperature of the material.

EXPERIMENTAL

The epoxy system used for this experiment was Araldite GY6010*/ Jeffamine® D230* epoxy resin/curing agent. The resin is a standard diglycidyl ether of Bisphenol A based epoxy (DGEBA), and the curing agent is a Polyetheramine. This system has a long (4-5 hour) “pot life” at room temperature. The “pot life” is the time the material is still workable (able to be poured, spread or applied) before it is cured.

The goal of the DSC experiment was to determine the T_g after the sample was cured for 72 hours at room temperature. Figure 4 shows the DSC scan, at 10 °C/min, of this material.

There are three events to point out.

1. The T_g can be seen in the step-change of the heat flow;
2. A large enthalpic recovery peak is seen; and
3. Additional curing and crosslinking upon heating above the T_g.

Even though the T_g can be seen it would be difficult to quantify the temperature due to the enthalpic recovery.

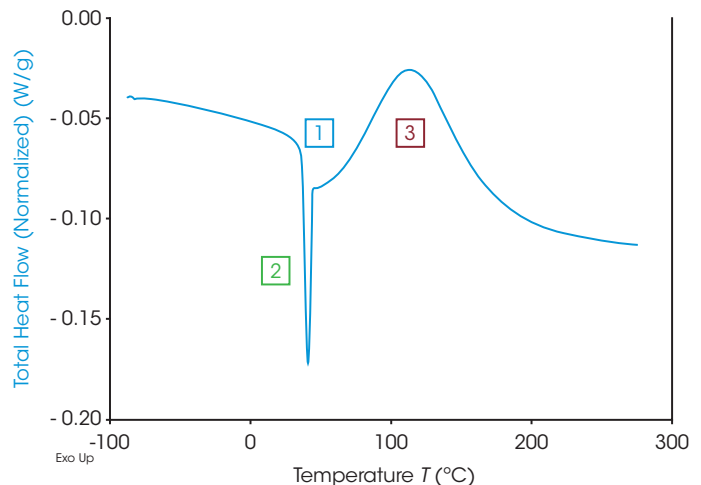


Figure 4. DSC of 72-hr cured epoxy

What is happening to make the DSC thermogram complicated?

This T_g appears to be between 25 °C and 50 °C. When the material is stored at room temperature it is below but close to the T_g. There is enough mobility for the sample to give up energy as discussed earlier, and therefore we see enthalpic recovery.

Why is there a residual crosslinking occurring after the T_g?

Recall that the epoxy was cured at room temperature. As the material crosslinks the T_g moves to higher temperatures. As the T_g rises to a temperature above the cure temperature, as clearly

occurred here, the sample goes through vitrification. This is the process of forming a “glass”, therefore dramatically lowering molecular mobility. This quenches the crosslinking reaction and the material does not fully cure. When the material is heated above the T_g , molecular mobility increases, and the curing will continue.

What if we do a Heat-Cool-Heat (H-C-H) experiment? Will that allow us to measure the T_g ?

Since we know the material undergoes further crosslinking during the first heat, any H-C-H experiment will only show the T_g after the sample is cured from the first heat, and not the desired “as received” value.

As previously discussed, the T_g is a heat capacity transition, while enthalpic recovery and crosslinking are kinetic transitions. MDSC can separate the heat capacity from the kinetic transitions. Figure 5 shows the MDSC data of the material, using the conditions described earlier. The Total Heat Flow signal is very similar to the standard DSC curve in Figure 4, but with MDSC two more signals are also available. The Reversing Heat Flow curve shows a clearly defined T_g with a midpoint of 40.28 °C, while the Non-Reversing Heat Flow curve shows the enthalpic recovery and the additional crosslinking.

As mentioned earlier, the goal was to determine the T_g of the material after curing at room temperature for 72 hours. MDSC shows this and the answer is approximately 40 °C.

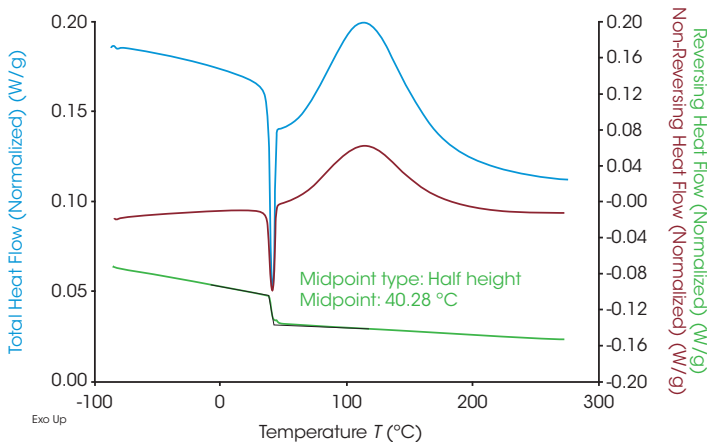


Figure 5. MDSC of 72-hr cured epoxy

CONCLUSION

DSC is commonly used to characterize a variety of materials exhibiting many different transitions. As DSC is relatively fast, and uses a relatively small sample, it is very often the first attempt to characterize these materials for thermal transitions. As shown, some transitions are not simple or clear in DSC. In cases where glass transitions are occurring around the same temperature as kinetic transitions, like an enthalpic recovery as shown in the paper, MDSC can separate these and allow for clearer interpretation of the data. MDSC is an important tool for the Thermal Analyst and is standard on all TA Instruments DSC's – Discovery X3 DSC, Discovery DSC 2500, 250, & 25. The Discovery X3 DSC allows 3 samples to be run at the same time for added productivity and the comparison of data under the same conditions.

ACKNOWLEDGEMENT

This paper was written by Louis Waguespack, Applications Laboratory Manager, and Tianhong (Terri) Chen, Ph.D., Senior Applications Support Scientist at TA Instruments.

REFERENCES

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2. Modulated DSC® Paper #1: Why Modulated DSC®?; An Overview and Summary of Advantages and Disadvantages Relative to Traditional DSC, TA Instruments Technical Paper (TP 0006).
3. Modulated DSC® Paper #2: Modulated DSC® Basics; Calculation & Calibration of MDSC® Signals, TA Instruments Technical Paper (TP 0007).

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